

SEMI® IMSG Executive Committee Meeting

July 12, 2004

Robert Scace, Klaros Corporation
Global Standards Subcommittee

SEMICON West 2004

Flat Panel Display
Business and Technical Education Programs
www.semi.org
Publications
International Standards
Workforce Development
Worldwide Offices
Industry Research & Statistics
Committees
Membership
Advocacy
Environment, Health & Safety
Expositions
Information Products
Executive Conferences

NA MEMS Standards Committee

- Committee co-chairs:
 - Michael Huff, MEMS Exchange
 - Dan Chilcott, Delphi
 - Win Baylies, BayTech (vice chair)
- Meetings:
 - Austin 15 October
 - La Jolla 15 March
 - San Francisco 12 July

NA MEMS Standards Task Forces

MEMS Fluidics Interface TF

Mark Crockett, Applied Materials; Bai Xu, Albany Univ.

Wafer-bonding Target TF

Win Baylies, BayTech

MEMS Test WG

Dan Chilcott, Delphi; Win Baylies, BayTech

MEMS Packaging WG

Charlie Cuneo, Unitek Benchmark

Process Steps WG (inactive; no leader at present)

Wafer Specifications for MEMS Applications TF

Graham Fisher, MEMC

NEW MEMS Materials Test WG

Dan Chilcott, Delphi; Janet Marshall, NIST; Kevin Turner, MIT

NA Activities Since Munich Meeting

Fluidics Interface TF meeting monthly by phone

Gathering information on definitions, existing roadmaps, design considerations

Drafting guide for Standard Performance, Practices, and Assembly

Advanced Semiconductor Manufacturing Conference, Boston 4-6 May

MEMS Film Properties Workshop ½ day

~40 attendees, excellent presentations

MEMS Materials Test WG formed

TFOF drafted; topics are MEMS film properties, wafer-wafer bond interfaces

Other materials characterization and modeling work tbd

Europe MEMS Standards Activities

Munich MEMS Committee 20 April 04

- Wafer Backside Exclusion Frame Size WG
handling methods, contact methods, contamination limits, exclusion zone size
- Universal Alignment Targets for Wafer Bonding WG
Coordinating with NA Wafer Bonding Target TF
- Terminology WG
Seeking existing definitions from EU, JA, NA sources
Coordinating with NA Fluidics and Packaging TFs
- MEMS Trays and Carriers WG
Coordinating with DIN if possible. DIN reluctant.

All WGs urged to submit TFOFs and SNARFs immediately

Japan MEMS Standards Activities

An IMSG Meeting is planned in August to discuss details of Workshop to survey the needs of Standards in this field.